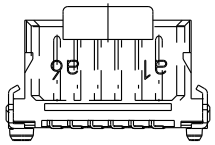
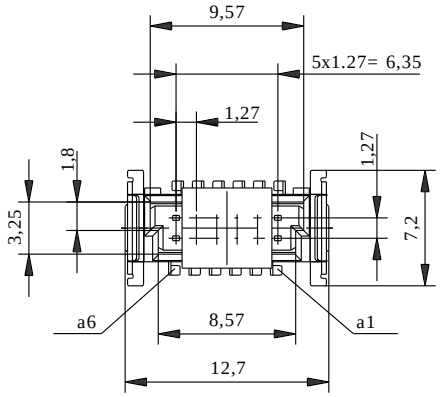
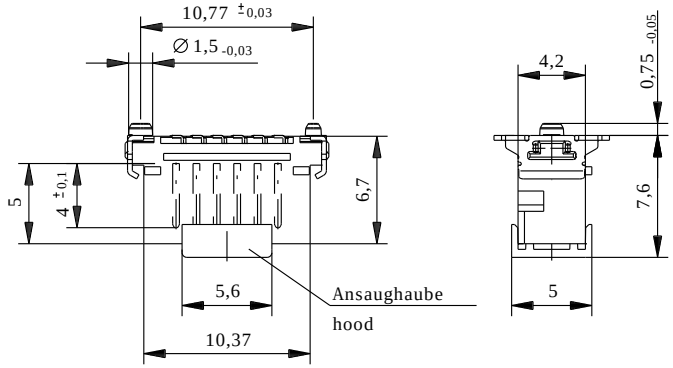
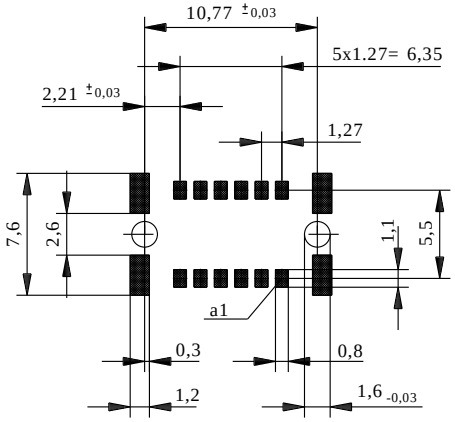






Leiterplatten-Layout Vorschlag für SMT

PCB-Layout Proposal for SMT



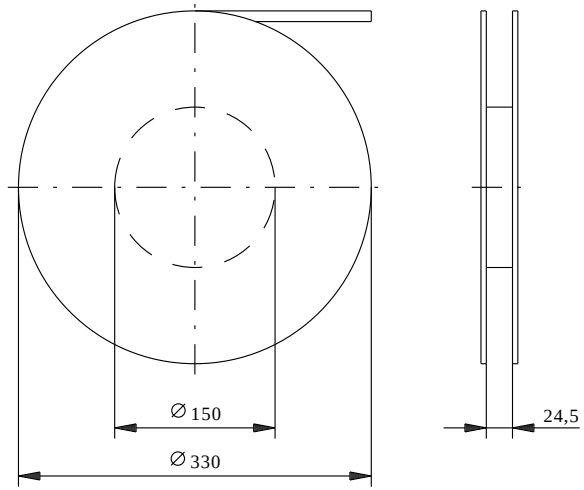
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

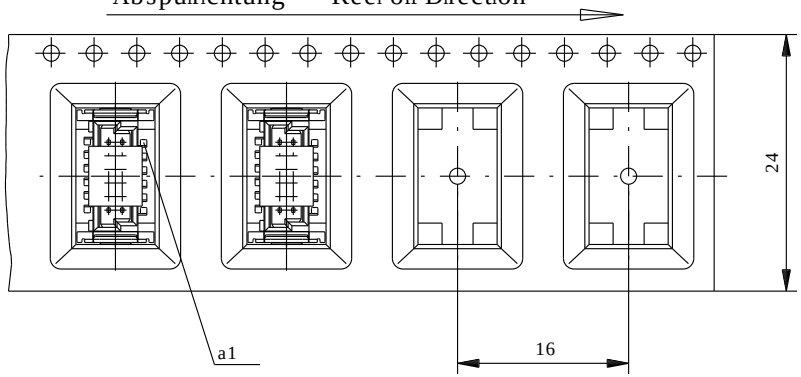
Anschlussbereich verzinnt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0.1mm
Coplanarity Area of Termination ≤ 0.1 mm

Verpackt in Gurtverpackung - Tape on Reel Packaging
Verpackungseinheit: 280 Stück - Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



BA7-13 - 8 mm Bauhöhe

type7-13 - Low Profile

Information:

Tolerances

All Dimensions in mm

Scale 3:1

Angaben zu entsprechender Ident-Nr. siehe Fertigungsunterlagen
For further information about I.D. number see manufacturing document.

All rights reserved.
Only for information.
To insure that this is the latest version of this drawing, please contact one of the ERNI companies before using.

Subject to modification without prior notice.
Drawing will not be updated.

Designation

Messerl. SMC-Q 12-SMD-BA7-13

Male SMC-Q 12-SMD-type7-13

ERNI www.ERNI.com

154818

Index	Date	
b	17.11.2005	V:00059753.SZA

SMC Q

Consider protection memo from DIN 34